NIKO-SEM

P-Channel Enhancement Mode Field Effect Transistor

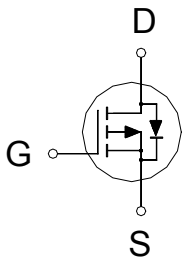
PB555BA

PDFN 2x2S

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-30V	25mΩ	-8A

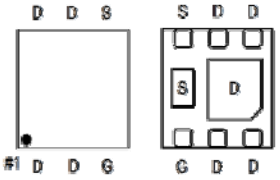


Features

- Pb−Free, Halogen Free and RoHS compliant.
- Low $R_{DS(on)}$ to Minimize Conduction Losses.
- Ohmic Region Good $R_{DS(on)}$ Ratio.
- Optimized Gate Charge to Minimize Switching Losses.

Applications

- Protection Circuits Applications.
- Logic/Load Switch Circuits Applications.



G : GATE
D : DRAIN
S : SOURCE

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_A = 25 °C	I_D	-8	A
	T_A = 70 °C		-6.4	
Pulsed Drain Current[1]		I_{DM}	30	
Power Dissipation[3]	T_A = 25 °C	P_D	2.7	W
	T_A = 70 °C		1.7	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient[2]	t ≦10s	$R_{\theta JA}$		45	°C／W
Junction-to-Ambient[2]	Steady-State	$R_{\theta JA}$		65	

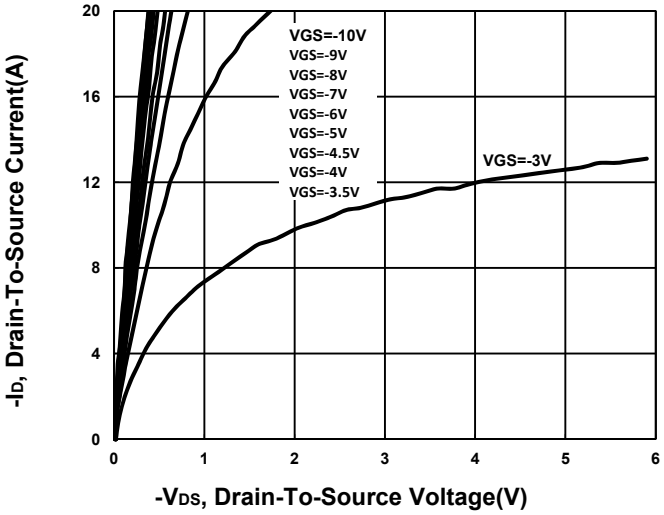
[1]Pulse width limited by maximum junction temperature.
[2]The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
[3]The Power dissipation is based on $R_{\theta JA}$ t ≦10s value.

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

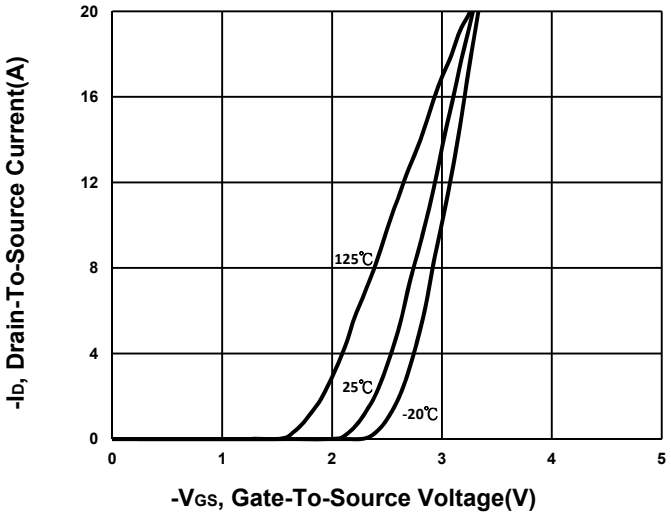
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS MIN	LIMITS TYP	LIMITS MAX	UNIT
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = -250μA	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -250μA	-0.8	-1.7	-2.5	V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = -24V, V_{GS} = 0V			-1	μA
		V_{DS} = -20V, V_{GS} = 0V, T_J = 55 °C			-10	μA
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = -10V, I_D = -6A		18	25	mΩ
		V_{GS} = -4.5V, I_D = -6A		29	40	mΩ
Forward Transconductance[1]	g_{fs}	V_{DS} = -5V, I_D = -6A		22		S
DYNAMIC						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = -15V, f = 1MHz		920		pF
Output Capacitance	C_{oss}			133		pF
Reverse Transfer Capacitance	C_{rss}			115		pF
Gate Resistance	R_g	V_{GS} = 0V, V_{DS} = 0V, f = 1MHz		13		Ω
Total Gate Charge[2]	$Q_{g(VGS=-10V)}$	V_{DS} = -15V , I_D = -6A		20		nC
	$Q_{g(VGS=-4.5V)}$			10		nC
Gate-Source Charge[2]	Q_{gs}			2		nC
Gate-Drain Charge[2]	Q_{gd}			5		nC
Turn-On Delay Time[2]	$t_{d(on)}$	V_{DD} = -15V $I_D \cong$ -6A, V_{GEN} = -10V, R_G = 6Ω		16		nS
Rise Time[2]	t_r			18		nS
Turn-Off Delay Time[2]	$t_{d(off)}$			40		nS
Fall Time[2]	t_f			26		nS
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)						
Continuous Current	I_S				-2.7	A
Forward Voltage[1]	V_{SD}	I_F = -6A, V_{GS} = 0V			-1	V
Reverse Recovery Time	t_{rr}	I_F = -6A , dI_F/dt = 100A / μS		11		nS
Reverse Recovery Charge	Q_{rr}			3.8		nC

[1]Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.
[2]Independent of operating temperature.

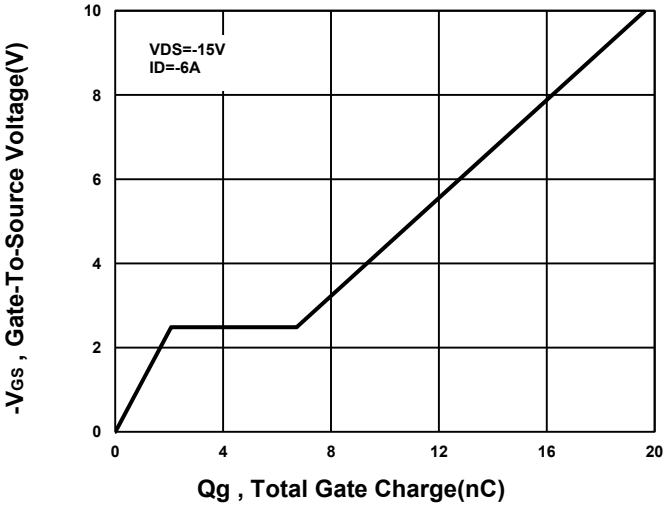
Output Characteristics



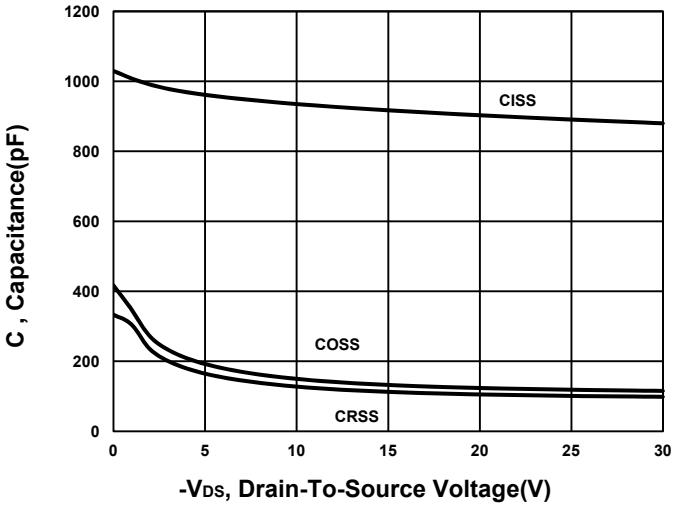
Transfer Characteristics



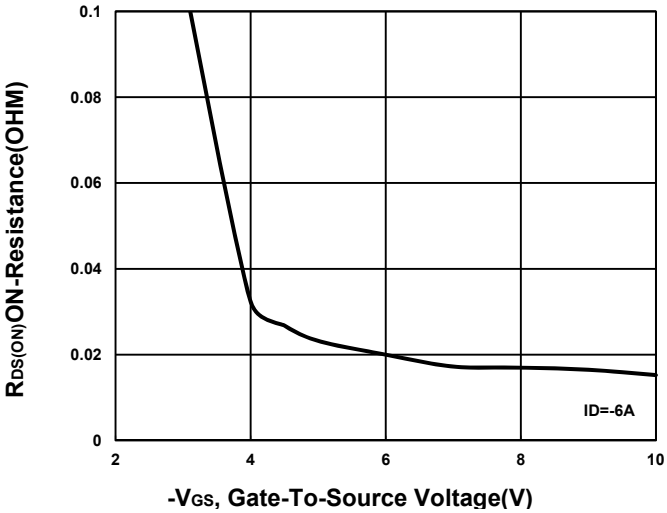
Gate charge Characteristics



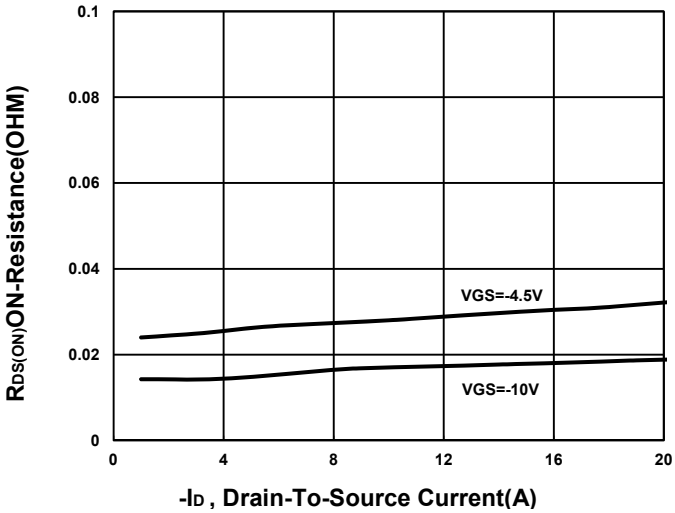
Capacitance Characteristic



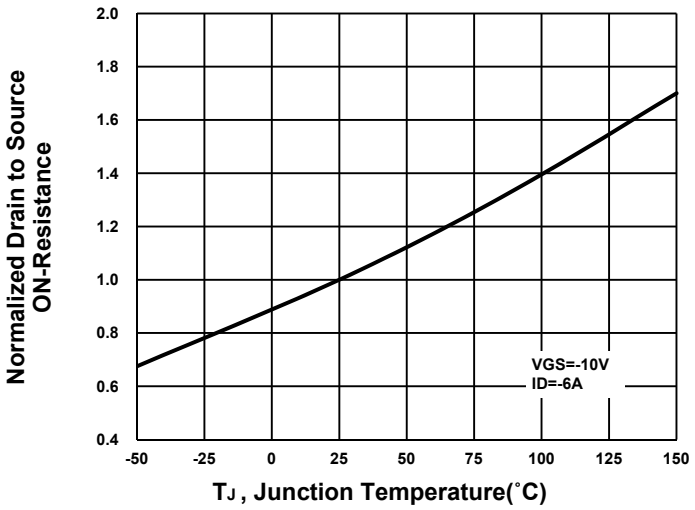
On-Resistance VS Gate-To-Source



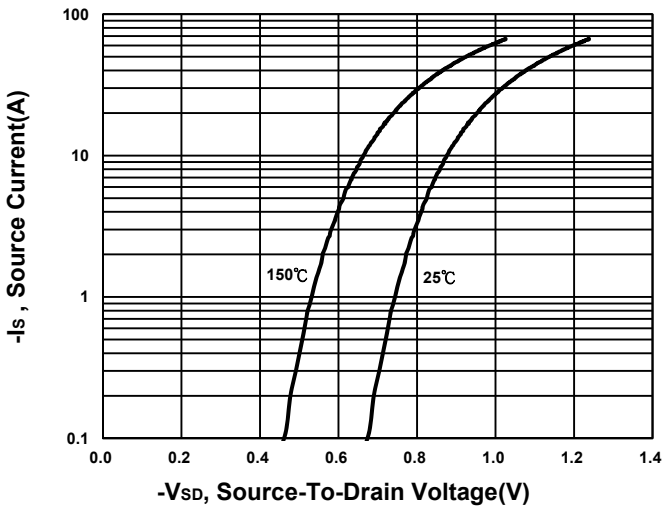
On-Resistance VS Drain Current



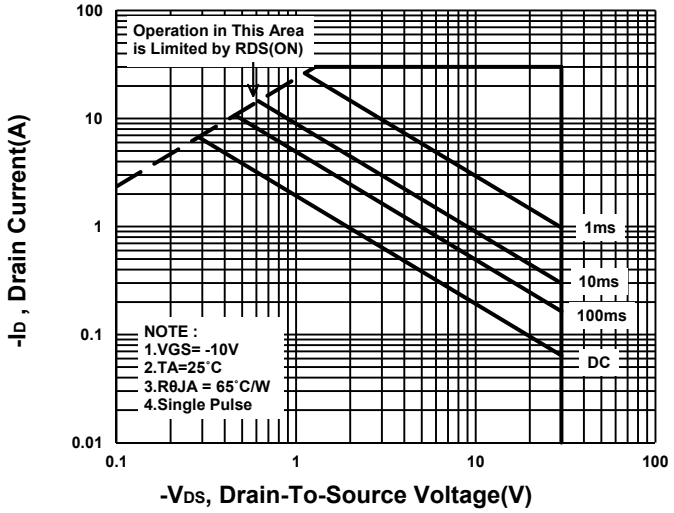
On-Resistance VS Temperature



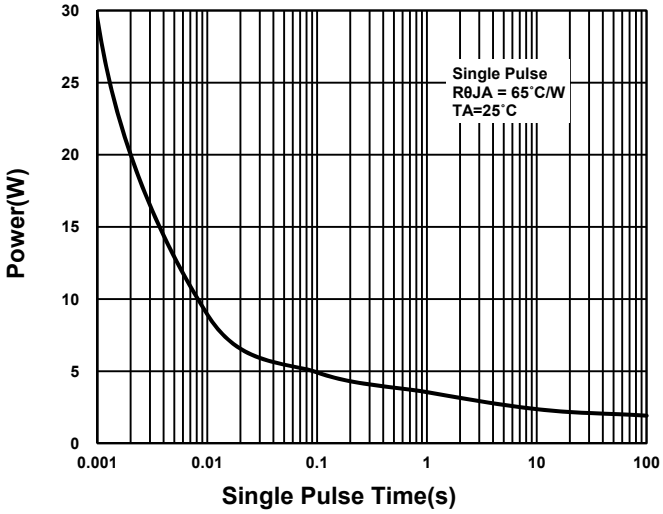
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve